

View Online at https://aerobasegroup.com/nsn/5910-01-318-4022

| Body Style: | |
|--|---|
| Chip type | |
| Reliability Indicator: | |
| Established | |
| Reliability Failure Rate Level In Percent: | |
| 0.001 | |
| Terminal Length: | |
| Between 0.010 inches and 0.030 inches | |
| Body Length: | |
| Between 0.165 inches and 0.200 inches | |
| Body Width: | |
| Between 0.235 inches and 0.270 inches | |
| Body Height: | |
| Between 0.020 inches and 0.080 inches | |
| Schematic Diagram Designator: | |
| No common or grounded electrode (s) | |
| Insulation Resistance At Maximum Operating Temp: | |
| 100000.0 megohms | |
| Capacitance Value Per Section: | |
| 150000.000 picofarads single section | |
| Voltage Tempurature Limits Per Section In Percent Capacitance Change: | |
| -25.0/+15.0 with rated voltage applied single section | |
| Nonderated Operating Temp: | |
| Between -55.0 degrees celsius and 125.0 degrees celsius | |
| Nonderated Continuous Voltage Rating And Type Per Section: | |
| 100.0 dc single section | |
| Tolerance Range Per Section: | |
| -10.00/+10.00 percent single section | |
| Case Material: | |
| Ceramic | |
| Insulation Resistance At Reference Temp: | |
| 1000000.0 megohms | |
| Dissipation Factor At Reference Tempurature In Percent: | |
| 2.500 | |
| Terminal Surface Treatment: | |
| Solder | |
| Test Data Document: | |
| 81349-mil-c-55681 specification (includes engineering type bulletins, brochures, etc., that reflect specification type data in specification | ı |
| format; excludes commercial catalogs, industry directories, and similar trade publications, reflecting general type data on certain | |
| environmental and performance requirements and test conditions that are shown as "typical", "average", "", etc.). | |
| Terminal Type And Quantity: | |
| 2 bonding pad | |

2 bonding pad

Specification Data:



Shelf Life:

N/a

Unit Of Measure:

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Demilitarization:

No

Fiig:

A010b0